

TECHNICAL DATA SHEET

STICKING WOOD FLOORING TO STONE OR TILE FLOORS (UG 14)

In the course of refurbishment measures, the question often arises of whether an existing tile or stone floor must be removed or whether it can be covered directly with parquet. This latter option is possible in principle, if certain working rules are taken into account. Residues of care products and wax, which form a separating layer, must be thoroughly removed. It is necessary to check whether the substrate is sufficiently load-bearing, firm and even; in particular, it must be checked whether the adhesion of the tiles to the substrate or screed is sufficiently strong. Loose or hollow-sounding tiles must be removed. In case of doubt, the tiles should be completely removed together with the tile adhesive. If the floor is uneven, it is necessary to level it out with levelling compound. It is preferable to install multilayer parquet, as less tension is transferred to the subfloor than with solid parquet or planks. For solid parquet, additional decoupling underlays are advisable; for multilayer parquet, the use of underlays can also be recommended for reasons of noise reduction and to increase walking comfort.

WE RECOMMEND THE FOLLOWING PROCEDURE:

- ✓ Completely remove any adhesive and carpet residues from the tiles, if existing. Thoroughly clean and degrease the surface; dirt and cleaning agent residues on the tiles form a separating layer and prevent the subsequent adhesive from "gripping". Grind tiles with a single disc machine or, better still, with a diamond milling disc. Ideally, the surface is distinctly roughened.
- ✓ All reactive adhesives (SMP, SPU and PUK types) are suitable for direct bonding to tiles, especially if the surface of the tiles is distinctly roughened.
- ✓ Perform subfloor inspection. The substrate should be stable, firm and absorbent. Loose tiles must be removed, adhesive residues at these places must also be removed. After priming with STAUF D 54 or VDP 130, for example, gaps or holes can be filled with the firm parquet levelling compound STAUF RM or the selflevelling compound STAUF XP 40. In principle, all reactive adhesives (STAUF SMP, SPU, PUK types) are suitable for direct bonding, especially if the surface of the tiles has

been distinctly roughened.

- ✓ Priming the tiles with STAUF VEP 195 2-component epoxy resin primer, application with a roller or a brush, usage approx. 300 g/m², sprinkling at least 2-3 kg quartz sand/m², allow to dry for 24 hours, remove loose sand by sweeping, rubbing, or vacuuming. If bonding is performed within 72 hours with STAUF SPU, PUK or SMP adhesives, sprinkling can be dispensed with.
- ✓ Alternatively, the tiles may also be primed with STAUF VDP 160 dispersion primer: Application with a roller, usage approx. 125 g/m², drying time approx. 90 minutes. Another alternative is WEP 180 2-component dispersion epoxy resin primer. Apply with a roller, usage approx. 200 g/m², sprinkle with 2-3 kg quartz sand, allow to dry for at least 5 hours, remove loose sand by sweeping, rubbing, vacuuming.

If levelling is necessary, STAUF XP 40 wood flooring levelling compound can be applied to the ready primed surface coated with STAUF VEP 195 and then well sprinkled, or to the ready primed surface previously coated with STAUF VDP 160. The levelled surface can then be directly bonded without any further priming. Mosaic parquet, strip parquet or multilayer parquet can also be bonded to the levelled surface using dispersion adhesive (M2A 720).

The information provided above corresponds to the current state of the art. The information is purely indicative and non-binding, since we have no control over the installation process and because the actual installation conditions on site vary. Therefore no claims can be made based on this information. The same is true for the commercial and technical advisory services that are provided without obligation and free of charge. We therefore recommend carrying out sufficient testing of your own in order to determine whether the result is suitable for the intended purpose.